Foamtec International
Wilshire Contamination Control Division
cleaning critical surfaces

APPLICATION NOTES
AMAT P5000 CVD CHAMBER

Problem: Processes that deposit a nitride passivation layer develop a residue on the inside of the chamber that is very difficult to remove. This layer is so difficult to remove that many users elect to merely wet wipe the chamber. The film is so tough and time consuming to remove with ScotchBrite®, that its removal is not worth the contamination that would be introduced by ScotchBrite®.

The use of the UltraSOLV® HT4536DS-10 diamond-based, slitted ScrubPAD allows for a much more thorough and faster clean of the chamber as compared with ScotchBrite®.

Procedure: The tech should mix and match the UltraSOLV® HT4536D-10 diamond-based ScrubPAD with an UltraSOLV® HT4540S-10 SIC-based, slitted ScrubPAD to clean the lid, lip and walls of the chamber. Since the chamber is normally cleaned at 65°C, then it is best to immediately wipe the recently scrubbed areas with the back of the ScrubPAD or an UltraSOLV® HT4790 Wiper, as to prevent re-adhesion to the chamber. DI H_2O is the desired solvent for this wet clean.

For final wiping, a combination of HT5790S MiraWIPE® Wiper, HT4790 UltraSOLV® Wiper, HT1701 and HT1700 UltraSOLV® Swabs should be used. Please be sure to follow the usage procedures as outlined in the 4500 “How to” document.

Required Supplies:

1 ea.	HT4536DS-10	UltraSOLV® ScrubPAD
1 ea.	HT4540S-10	UltraSOLV® ScrubPAD
5-10 ea.	HT4790	UltraSOLV® Wiper
5 ea.	HT5790S	MiraWIPE® Wiper
5-10 ea.	HT1700 and HT1701	UltraSOLV® Swab